Die Attach Adhesives

DIE ATTACH FILM

Product Name	Description	Key Attributes	Glass Transition Temperature, T_g (°C)	Viscosity at 25°C	Coefficient of Thermal Expansion, CTE (ppm/°C)		Modulus at 25°C (MPa)	Recommended Cure
					Below T_g	Above T_g		
Non-Conductive								
LOCTITE ABLESTIK ABP 2035SCR	Silica-filled die attach adhesive	• One component • Low stress • Snap cure or low temperature oven cure • Excellent dispensing performance for high throughput applications • Compatible with dam and fill encapsulants	118	9,830 at 5 rpm	50	135	1,500	2 min. at 120°C
LOCTITE ABLESTIK ABP 2024	BMI hybrid die attach adhesive	• Low outgassing • One component • High reliability	47	13,000 at 5 rpm	127	156	510	30 min. ramp + 30 min. hold at 175°C
LOCTITE ABLESTIK ABP 2040 LV	Epoxy non-conductive die attach adhesive	• One component • Fast cure • Low temperature cure • Low stress • Low warpage	28	11,000 at 5 rpm	39	129	2,603	2 min. at 120°C
LOCTITE ABLESTIK GA 2W	Acrylic die attach adhesive	• Very low stress • Low chip warpage • Improved viscosity • Thixotropic • Good dispensability • One component	25	10,000 at 5 rpm	58	164	70	30 min. ramp + 15 min. hold at 175°C

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LOCTITE®

Die Attach Adhesives

DIE ATTACH PASTE

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